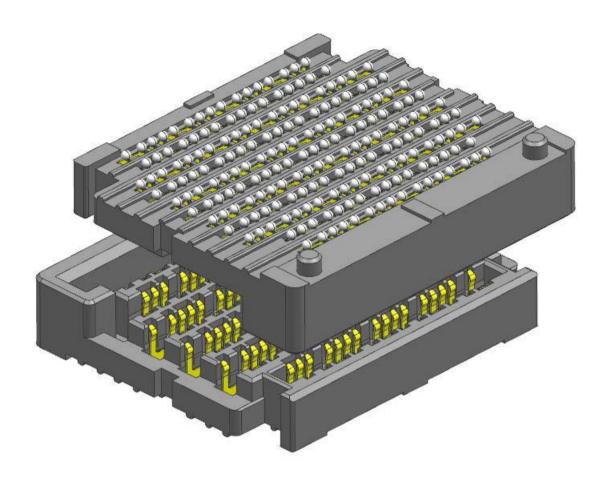


# $\frac{\textbf{RESTRICTED PRODUCT SPECIFICATION}}{\textbf{FOR MIRROR MEZZ}^{TM}}$



### TENTATIVE RELEASE:

THIS SPECIFICATION IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. PRELIMINARY TEST DATA MAY EXIST BUT THIS SPECIFICATION IS SUBJECTED TO CHANGE BASED ON RESULTS OF ADDITIONAL TESTING AND EVALUATION.

FORMATION

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# PRODUCT SPECIFICATION

### 1.0 SCOPE

This Product Specification covers the performance requirement and testing methods for Mirror Mezz™ connectors.

### 2.0 PRODUCT DESCRIPTION

### 2.1 PRODUCT NAME AND SERIES NUMBER(S)

Mirror Mezz™:

202828 209311

204843 211454

204358 209141

203456

206306

### 2.2 SAFETY AGENCY APPROVALS

TO BE CERTIFIED WITH UL/CSA

### 3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

EIA-364-1000 / IPC-9701

### 4.0 RATINGS

### 4.1 VOLTAGE

Recommended: 30 Volts AC (RMS) / VDC and below

30~60 Volts AC(RMS) / VDC application, please consult Molex for details

### **4.2 CURRENT**

0.75A per pin for 1 oz. Cu Trace

1.0A per pin for 1.5 oz. Cu Trace

1.2A per pin for 2 oz. Cu Trace

### 4.3 OPERATING TEMPERATURE

- 55°C to + 105°C

### 4.4 DURABILITY

100 Cycles

FOR FORMATION

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### **5.0 PERFORMANCE**

### **5.1 ELECTRICAL REQUIREMENTS**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
1	Contact Resistance (Low Level)	Mate connectors: apply a maximum voltage of 20 mV and a current of 100 mA.  Per EIA-364-23.	30 milliohms MAXIMUM [initial]
2	Insulation Resistance	Un-mate & unmount connectors: apply a voltage of 500VDC between adjacent terminals and between terminals to ground.  Per EIA-364-21.	1000 Megohms MINIMUM Signal/Signal
3	Dielectric Withstanding Voltage	Mated connectors: apply a voltage of 500 VAC (RMS) for 1 minute between adjacent terminals.  Per EIA-364-20.	No breakdown; current leakage < 5 mA
4	Signal Continuity	Mate connectors.  Per EIA-364-87.	No interrupts > 10 nanoseconds
5	Temperature Rise	Mate connectors. Apply a current of 0.75A for 1 oz. Cu trace to 6 adjacent terminals (GGSSGG) on the outer row and measure temperature rise of 2 middle (SS) terminals.  Mate connectors. Apply a current of 1.2A for 2 oz. Cu Trace and measure temperature rise.	Temperature rise: 30°C MAXIMUM



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### **5.2 MECHANICAL REQUIREMENTS**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
6	Connector Mate and	Mate and un-mate connector at a rate of 25 ± 6 mm per minute.	0.35 N per Pin MAX Avg. mating force &
	Un-mate Forces	Per EIA-364-13.	0.045 N per Pin MIN Avg. un-mating force
7	Durability	Mate connectors up to 100 cycles at a maximum rate of 10 cycles per minute.  Per EIA-364-09.	10 milliohms MAXIMUM (change from initial)
8	Vibration (Random)	Mate connectors and vibrate 20-500Hz Random, 3.1g's. 15 minutes, 3 axes.  Per EIA 364-28, test condition VII, condition D.	10 milliohms MAXIMUM (change from initial) & Discontinuity < 10 nanosecond
9	Shock (Mechanical)	Mate connectors and shock at 30 g's with ½ sine wave (11 milliseconds) shocks in the ±X, ±Y, ±Z axes (18 shocks total).  Per EIA-364-27, condition H.	10 milliohms MAXIMUM (change from initial]) & Discontinuity < 10 nanosecond
10	Contact Normal Force	Deflect contacts at a rate of 25.4mm +/- 0.20mm per minute. Take normal force measurements at nominal deflection.  Per EIA-364-04	0.2 N MINIMUM contact normal force per pin

### **5.3 ENVIRONMENTAL REQUIREMENTS**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
11	Thermal Shock	Mate connectors; expose to 10 cycles of: -55°C to 85°C.  Per EIA-364-32, Test Condition 1.	10 milliohms MAXIMUM (change from initial) & Visual: No Damage
12	Temperature Life (Mated)	Mate connectors; expose to: 240 hours at 105 ± 2°C.  Per EIA-364-17	10 milliohms MAXIMUM (change from initial]) &  Visual: No Damage

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13	Cyclic Humidity (Mated) Thermal Disturbance	Mate connectors: 10 cycles at temperature 25 ± 3°C at 80%-98% relative humidity and 65 ± 3°C at 90%-98% relative humidity.  Per EIA-364-31, method III, omitting 7b vibration test.  {Note: Remove surface moisture and air dry for 1 hour prior to measurements.}  Cycle the connector between 15 ± 3°C and 85 ± 3°C as measured on the connector contacts. Ramps should be a minimum of 2°C per minute, and dwell times should insure that the contacts	10 milliohms MAXIMUM (change from initial) & Visual: No Damage
14		and 85 ± 3°C as measured on the connector contacts. Ramps should be a minimum of 2°C per minute, and dwell	
		reach these temperature extremes (a minimum of 5 minutes). Humidity is not controlled. Perform 10 cycles on Mated connectors.	10 milliohms MAXIMUM (change from initial]) & Visual: No Damage
		Per EIA-364-1000, table 4.	
15	Thermal Cycling	Cycle the connector between 15 ± 3°C and 85 ± 3°C as measured on the connector contacts. Ramps should be a minimum of 2°C per minute, and dwell times should insure that the contacts reach these temperature extremes (a minimum of 5 minutes). Humidity is not controlled. Perform 500 cycles on Mated connectors.  Per EIA-364-1000, table 5.	10 milliohms MAXIMUM (change from initial]) & Visual: No Damage
16	Dust	Use benign dust. Only one half of the unmated connector shall be exposed to dust and then mated to unexposed half.	10 milliohms MAXIMUM (change from initial)
		Per EIA-364-91.	
17 N	Mixed Flowing Gas (MFG)	10 days Un-mated, 4 days Mated.  Per EIA-364-65, method 2A  FORMAT  INFORMAT	10 milliohms MAXIMUM (change from initial) & Visual: No Damage

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## PRODUCT SPECIFICATION

### 6.0 TESTING REQUIREMENTS

### **6.1 TEST SEQUENCE**

Follow test sequence outlined in section 6.3 of this document.

### 6.2 IPC-9701 TEMPERATURE CYCLING TEST FOR SOLDER JOINT RELIABILITY

- 1. Cycle Condition TC1: 0 °C to +100 °C.
- 2. Test Duration: Whichever condition occurs first:

63.2% cumulative failure or 6,000 cycles

- 3. Temperature Profile
  - a. Low Temperature Dwell: 10 minutes +0/-5 °C.
  - b. High Temperature Dwell: 10 minutes +5/-0 °C.
  - c. Temperature Ramp Rate: Less than or equal to 20 °C /minute.
- 4. Sample Size: 32 mated sets and 10 reworked mated sets

(42 total test samples plus one for cross-section)

- a. Package condition: Daisy-Chain
- b. Monitoring: In-Situ Event Detection
- c. If this test is terminated prior to 6000 cycles, then use the Dye/Pry method to assess the solder joints. If 90% or greater dye penetration, then that solder joint is counted as a failure.
  - Categorize failures as follows:

Type I: Between the terminal paddle and solder-ball

Type II: Within solder-ball

Type III: Between solder-ball and soldering pad

Type IV: Between soldering pad and Board.



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# **PRODUCT SPECIFICATION**

### 6.3 EIA-364-1000

Seguence Croun 1 Croun 2 Croun 2 Croun 4 Croun 5 Croun 6 Croun 7						Group 7	
Sequence	Group 1	Group 2	Group 3	Group 4	Group 5	Group 6	Group 7
1	LLCR	LLCR	LLCR	LLCR	LLCR	LLCR	LLCR
2	Durability* (preconditioning)	Durability* (preconditioning)	Durability* (preconditioning)	Durability* (preconditioning)	Durability* (preconditioning)	Durability* (preconditioning)	DWV
3	LLCR	LLCR	LLCR	LLCR	LLCR	LLCR	Durability
4	Temperature Life	Thermal shock	Vibration	Temperature Life** (preconditioning)	Temperature Life** (preconditioning)	Dust	LLCR
5	LLCR	LLCR	LLCR	LLCR	LLCR	LLCR	DWV
6	Reseating (3 M/U cycles)	Cyclic Temperature & humidity	Shock	Mixed Flowing Gas	Thermal Cycling	Thermal Disturbance	-
7	LLCR	LLCR	LLCR	LLCR	LLCR	LLCR	-
8	-	Reseating (3 M/U Cycles)	-	Thermal Disturbance	Reseating (3 M/U cycles)	Reseating (3 M/U cycles)	-
9	-	LLCR	-	LLCR	LLCR	LLCR	-
10	-	-	-	Reseating (3 M/U cycles)	-	-	-
11	-	-	-	LLCR	FOR TION	-	-
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Durability\* preconditioning - perform 20 unplug/plug cycles Temperature Life\*\* preconditioning – 48 hours @ 115degC, mated.

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